



Click [here](#) for the 3D model.

| Dimensions | |
|------------|--|
| Chip Size | 2225 |
| L | 5.588mm +/-0.381mm (0.22 in +/-0.015 in) |
| W | 6.35mm +/-0.381mm (0.25 in +/-0.015 in) |
| T | 1.778mm MAX (0.07 in MAX) |

| Packaging Specifications | |
|--------------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 25000 |

| General Information | |
|---------------------|--|
| Series | SMD Mil PRF123 |
| Style | SMD Chip |
| Description | SMD Chip, Ultra Stable |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov . |
| SCIP Number | 646e40c8-ce81-456e-b9ed-50112f3d27a5 |
| Termination | Nickel |
| Failure Rate | N/A |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---------------------|
| Capacitance | 1500 pF |
| Capacitance Tolerance | 5% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BP |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vms |
| Dissipation Factor | 2.5% |
| Insulation Resistance | 100 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)